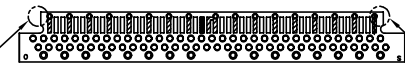


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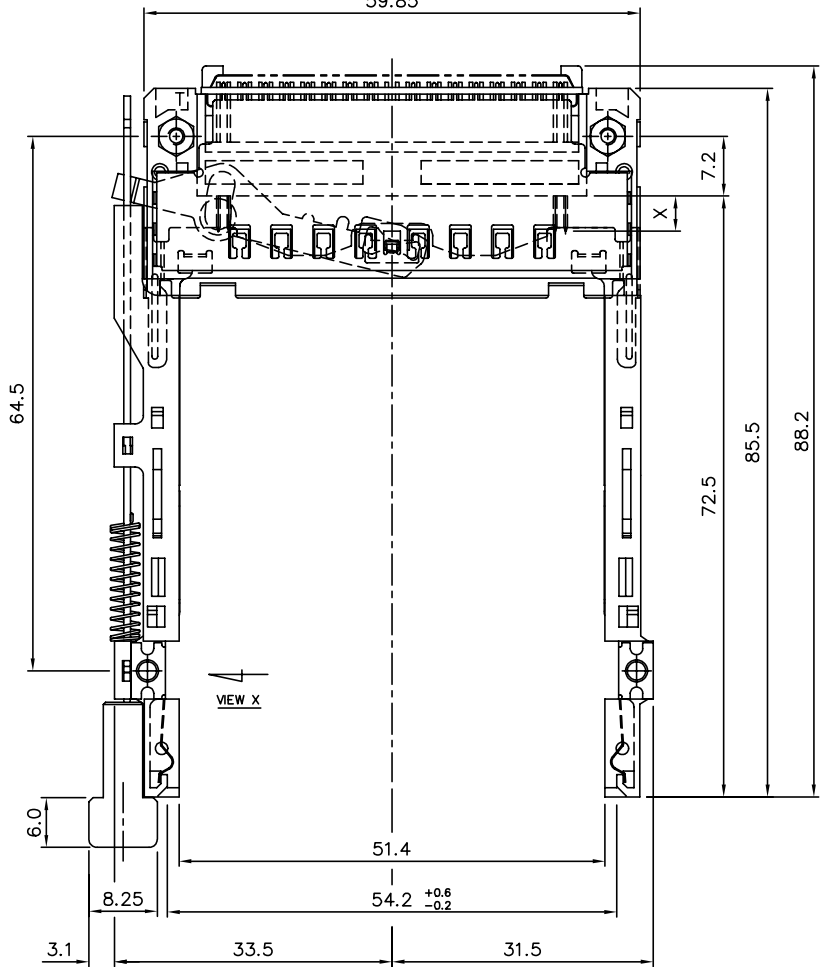
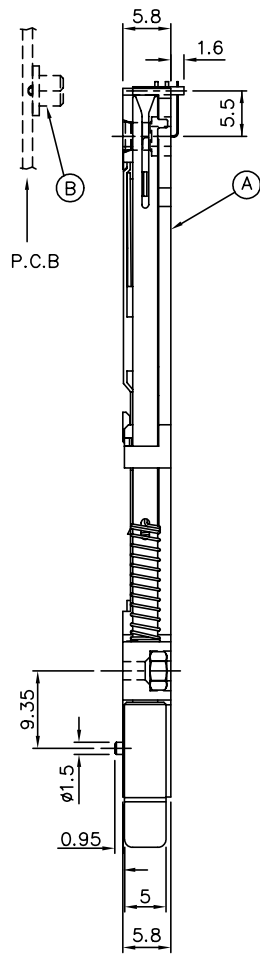


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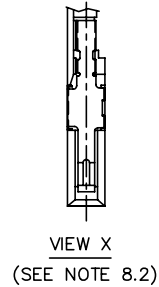
PRODUCT NO.
 52366-100DAS/100DASLF

SEE NOTE 8.1  SEE NOTE 8.1

PCB TOP VIEW
 (SEE NOTE 8.1)



VIEW X



VIEW X
 (SEE NOTE 8.2)

NOTES:

- 8.0mm MIN CARD EJECT.
- EJECT TRAVEL: 9.50mm
- MATERIAL:
 EJECT HEADER ASS'Y
 PLASTIC HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 PIN: COPPER ALLOY
 PCB: FR4
 PLASTIC GUIDE: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 PLATE: STAINLESS
 EMI CONTACT: PHOSPHOR BRONZE
- FINISH
 PIN:
 UNDER PLATING: 0.5um MIN. Ni
 CONTACT AREA: 0.076 μm MIN. GOLD
 SOLDER TAIL(TIN LEAD OPTION): 2.5um MIN. Sn-Pb
 SOLDER TAIL(LEAD FREE OPTION): 2.5um MIN. PURE TIN
 GROUND SHIELD:
 UNDER PLATING: 0.75um MIN. Ni
 CONTACT SURFACE: 0.2 um GOLD.
- PUSH ROD LOCATION AND P.C.B. ARE AS APPEARS INSTALLED
- DIM "X"

	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68	
- DO NOT TOUCH AND KEEP CLEAN THE SURFACES OF PCB OF HEADER ASS'Y.
- SPECIAL FEATURES:
 8.1 NO CHAMFER OF VTB
 8.2 NO "S"-SLOT
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263

ORDERING INFORMATION

NAME	PART NO.	Q'TY
(A) EJECT HEADER ASS'Y	52366-100DAS/100DASLF	1
(B) MATING RECEPTACLE	73277-101002/101002LF	1

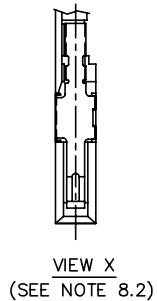
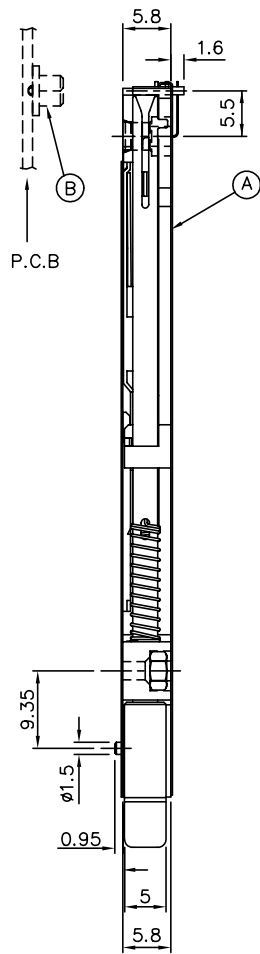
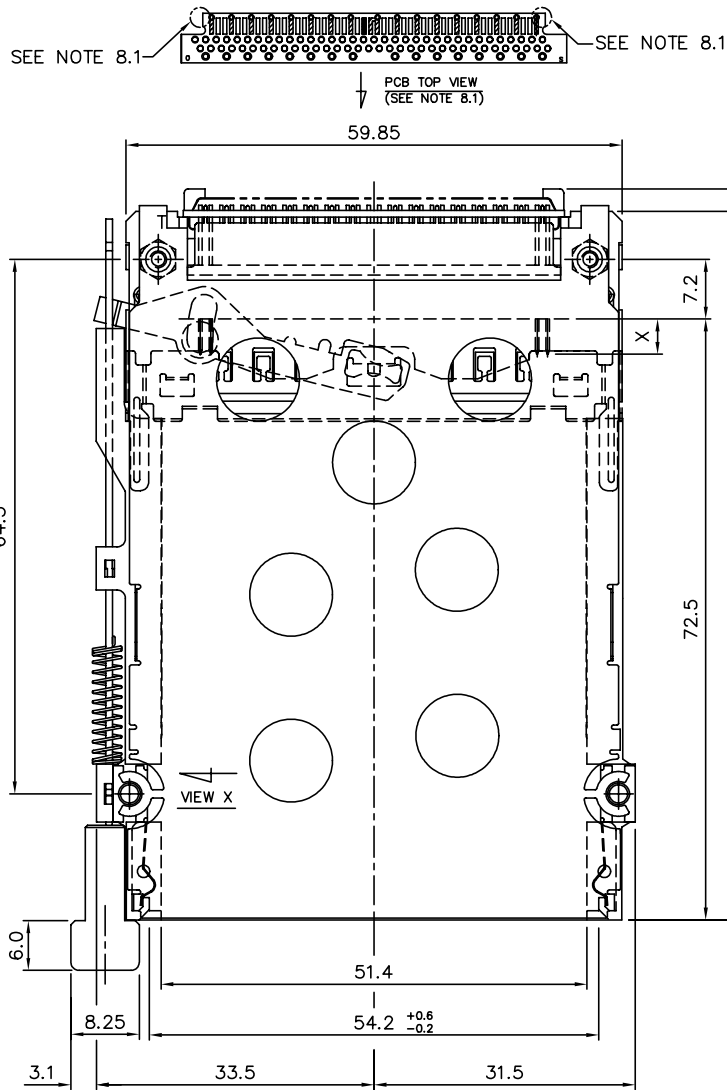
mat'l code				tolerance unless otherwise specified		CUSTOMER COPY		FCJ www.fcjconnect.com	
rev.	ecn no.	dr	date	linear	± 0.30	projection	title CARDBUS EJECT HEADER		
A	T90248	WL	07/06/99				FORCE-SAVING, TYPE 1/2/3		
B	T90287	WL	08/03/99				product family : PCMCIA		
C	T90359	WL	10/14/99	angles	± 2°		size	dwg no.	code
D	T00105	WL	04/11/00	dr	WENDY CHEN	06/25/99	mm/inch		TWN
E	T10151	WL	05/28/01	engr	STELAR CHU	06/25/99	scale		sheet
F	N05-0037	WB	02/16/05	chr	JOSEPH HSIAO	06/25/99	1.5:1	A3	1 OF 3
G	ELX-N-011388	ZK	04/02/12	appd	JENN TSAO	06/25/99		52366	
sheet	revision	G	G	G					
index	sheet	1	2	3					

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PRODUCT NO.
52366-300DAS/300DASLF



NOTES:

- 8.0mm MIN CARD EJECT.
- EJECT TRAVEL: 9.50mm
- MATERIAL:
EJECT HEADER ASS'Y
PLASTIC HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN: COPPER ALLOY
PCB: FR4
PLASTIC GUIDE: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE: STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH
PIN :
UNDER PLATING: 0.5um MIN. Ni
CONTACT AREA: 0.076 µm MIN. GOLD
SOLDER TAIL(TIN LEAD OPTION): 2.5um MIN. Sn-Pb
SOLDER TAIL(LEAD FREE OPTION): 2.5um MIN. PURE TIN
GROUND SHIELD :
UNDER PLATING: 0.75um MIN. Ni
CONTACT SURFACE: 0.2 um GOLD.
- PUSH ROD LOCATION AND P.C.B. ARE AS APPEARS INSTALLED
- DIM "X"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
- DO NOT TOUCH AND KEEP CLEAN THE SURFACES OF PCB OF HEADER ASS'Y.
- SPECIAL FEATURES:
8.1 NO CHAMFER OF VTB
8.2 NO "S"-SLOT
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263

ORDERING INFORMATION

NAME	PART NO.	Q'TY
(A) EJECT HEADER ASS'Y	52366-300DAS/300DASLF	1
(B) MATING RECEPTACLE	73277-101002/101002LF	1

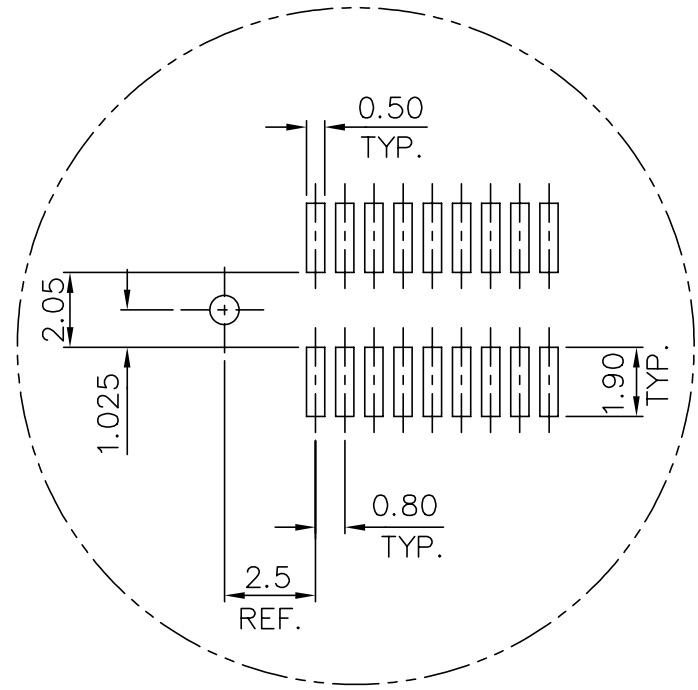
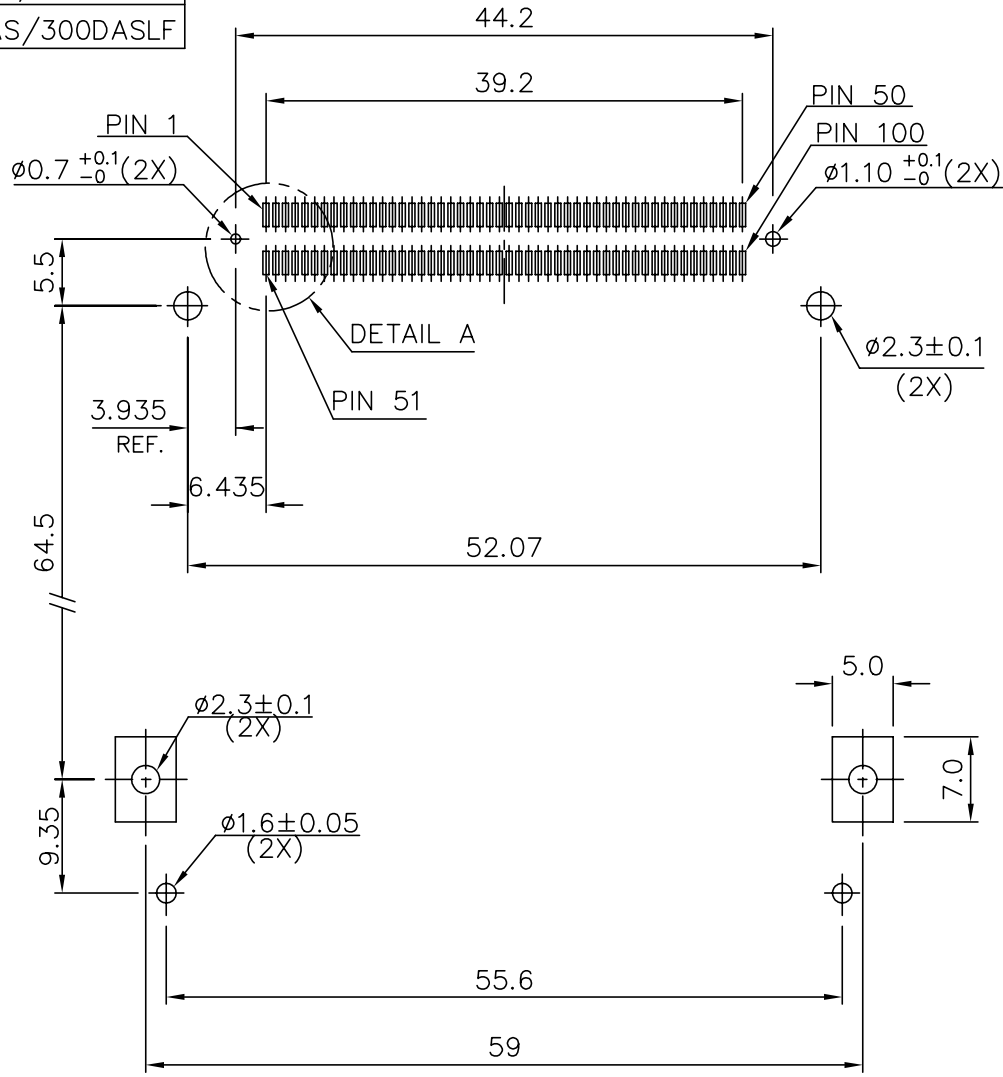
mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		 www.fcjconnect.com	
rev.	ecn no.	dr	date	linear	± 0.30	projection	title CARDBUS EJECT HEADER FORCE-SAVING, TYPE 1/2/3
G				angles	± 2°		
				dr	WENDY CHEN	06/25/99	product family : PCMCIA
				engr	STELAR CHU	06/25/99	
				chr	JOSEPH HSIAO	06/25/99	size
				appd	JENN TSAO	06/25/99	scale
						1.5:1	A3
sheet		revision		dwg no.		52366	
index		sheet		scale		TWN sheet 2 of 2	

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PRODUCT NO.
52366-100DAS/100DASLF
52366-300DAS/300DASLF



DETAIL A

4 CARD INSERTION DIRECTION

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		www.fciconnect.com	
rev.	ecn no.	dr	date	linear	± 0.10	projection	title CARDBUS EJECT HEADER SMT, TYPE 1/2/3
G				angles	± 2°		
				dr	WENDY CHEN 06/25/99	unit	product family : PCMCIA
				enrg	STELAR CHU 06/25/99	mm/inch	code
				chr	JOSEPH HSIA 06/25/99	scale	TWN
				appd	JENN TSAO 06/25/99	2:1	sheet
sheet	revision						3 OF
index	sheet						